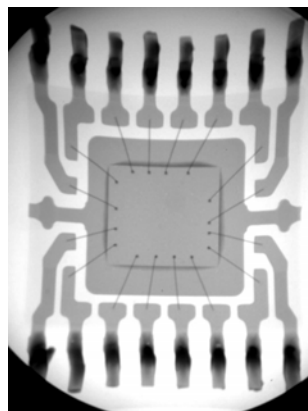


- **CONSTRUCTION ANALYSIS**

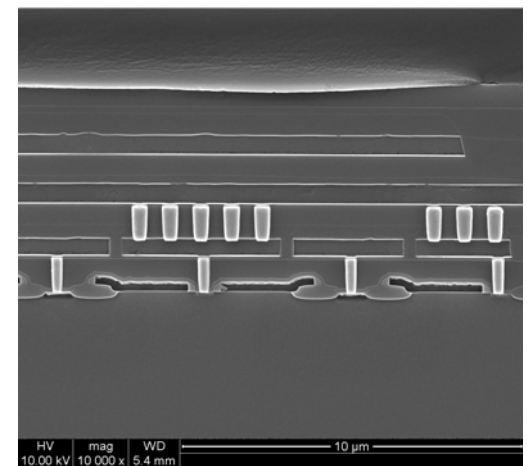
- This analysis can check your process to ensure that the device is made according to your specifications. It can also be used as a Competitor Analysis comparison. The report can include the following depending on your requirements and the depth of information you need.
- Real Time X-Ray – package and assembly info
- Die Photo – to document layout
- Bond Pad Dimensions
- Deprocessing to view each layer layout.
- Cross-Section – Die to show number of metal layers/minimum line pitch/barrier layers present/poly construction info – spacers & silicide/poly gate length/Via construction/materials/oxide thickness/die seal area, etc. as requested
- Cross-Section – Package to show package via type and quality/bump construction and quality, etc. as requested.



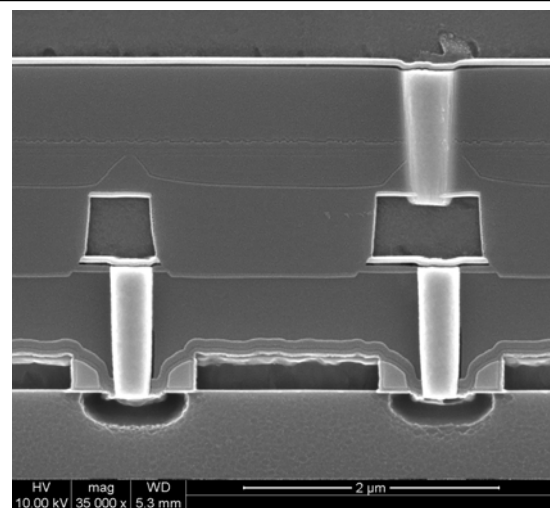
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Typical Package X-ray



Typical Cross-Section showing vias and contacts



Typical Cross-Section close up of poly and contacts

Nanolab Technologies Incorporated
 3833 North First Street
 San Jose, California 95134
 Telephone: 408-433-3320
 Fax: 408-433-3321
 Website: www.nanolab1.com

John P. Traub 408-230-9568
johnp@nanolab1.com

John P. Traub II (JT) 408-829-8708
jt@nanolab1.com